

STM32WB09_QFN32_2L_IPD

MB2157

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Sheet 1: Project overview (this page)

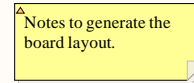
Sheet 2: STM32WB09_QFN32_RefBoard_IPD_2Layers

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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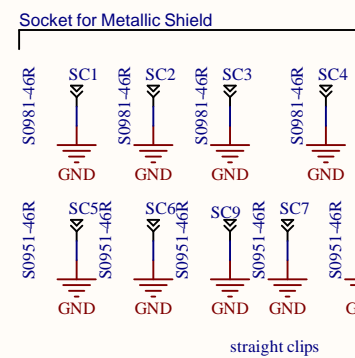
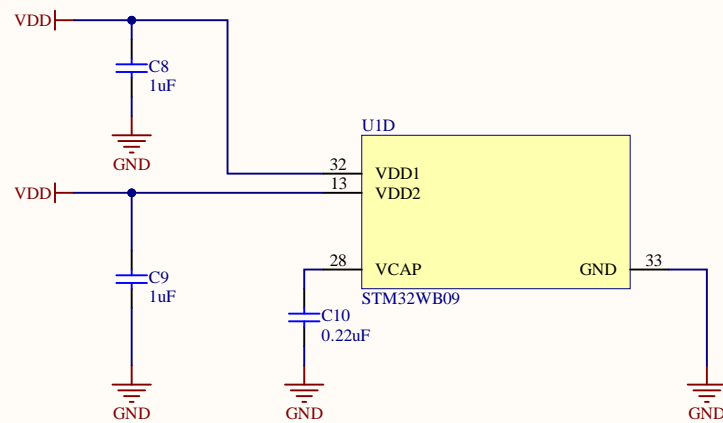
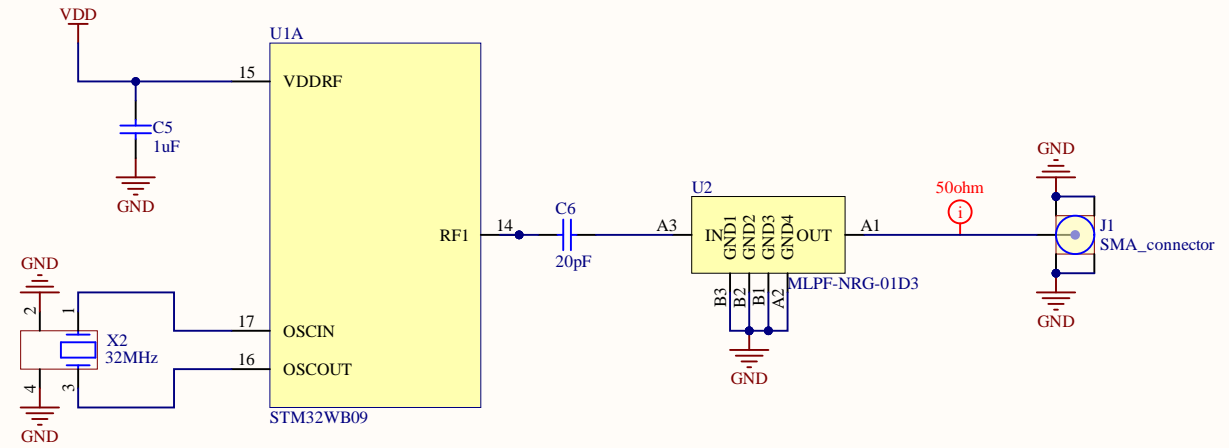
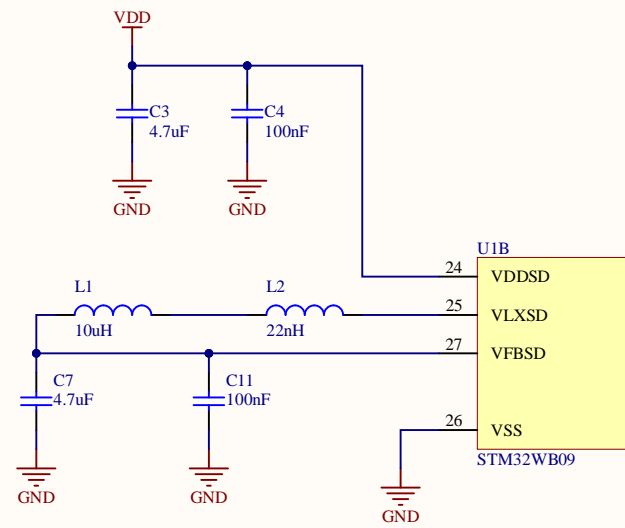
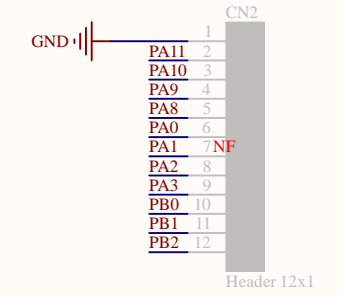
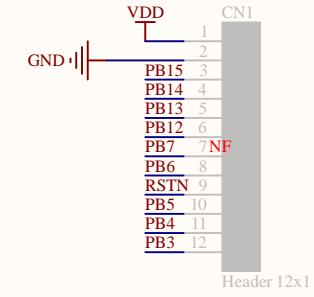
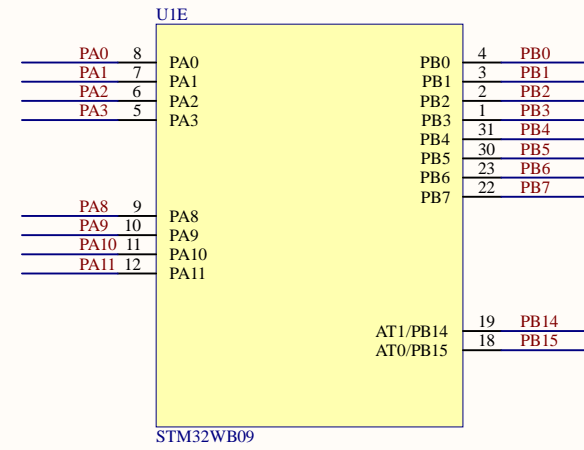
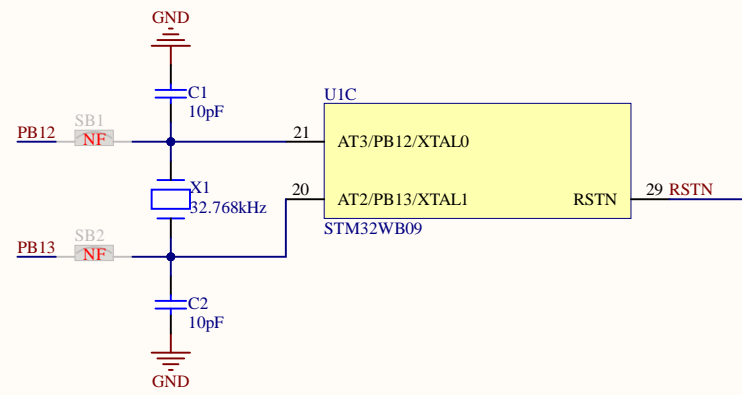
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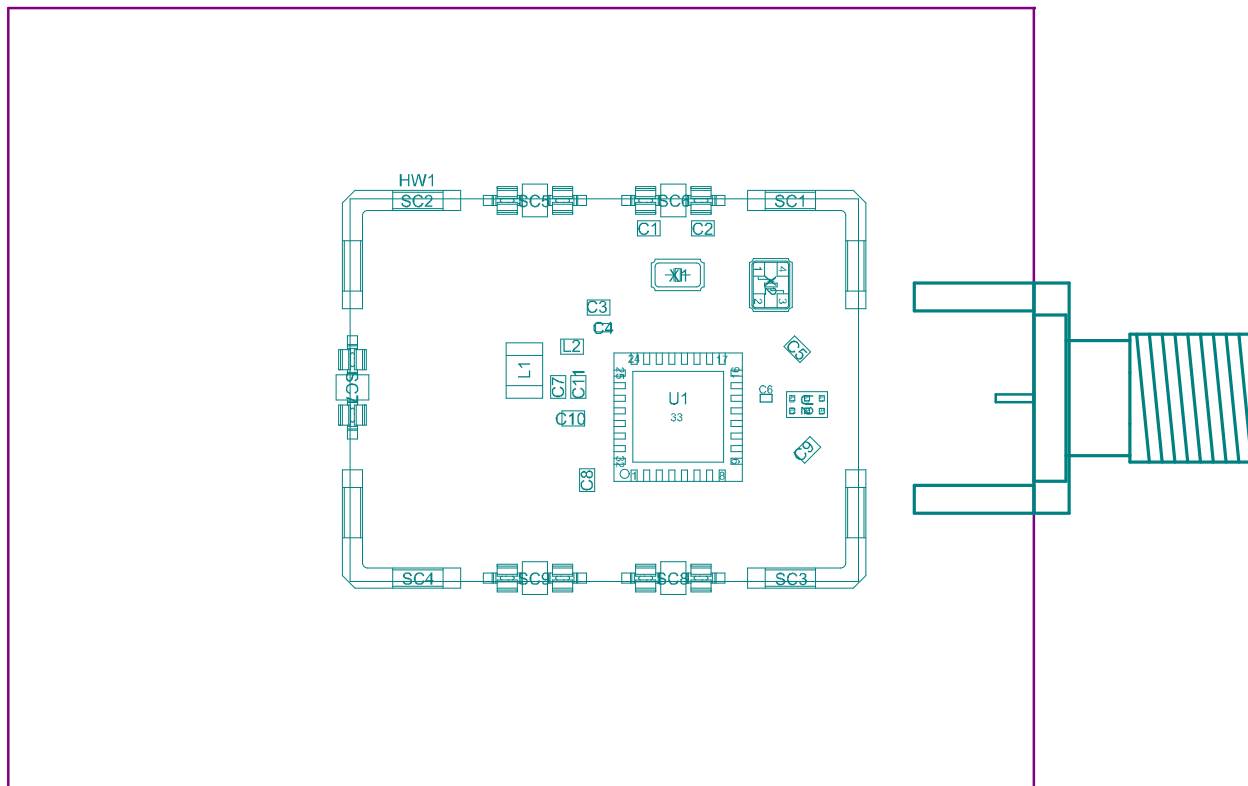
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STM32WB09_QFN32_RefBoard_IPD_2Layers.SchDoc




Title: Project overview		
Project: STM32WB09_QFN32_2L_IPD		
Variant: Variant A		
Revision: A-01		Reference: MB2157
Size: A4	Date: 07 July 2024	Sheet: 1 of 2

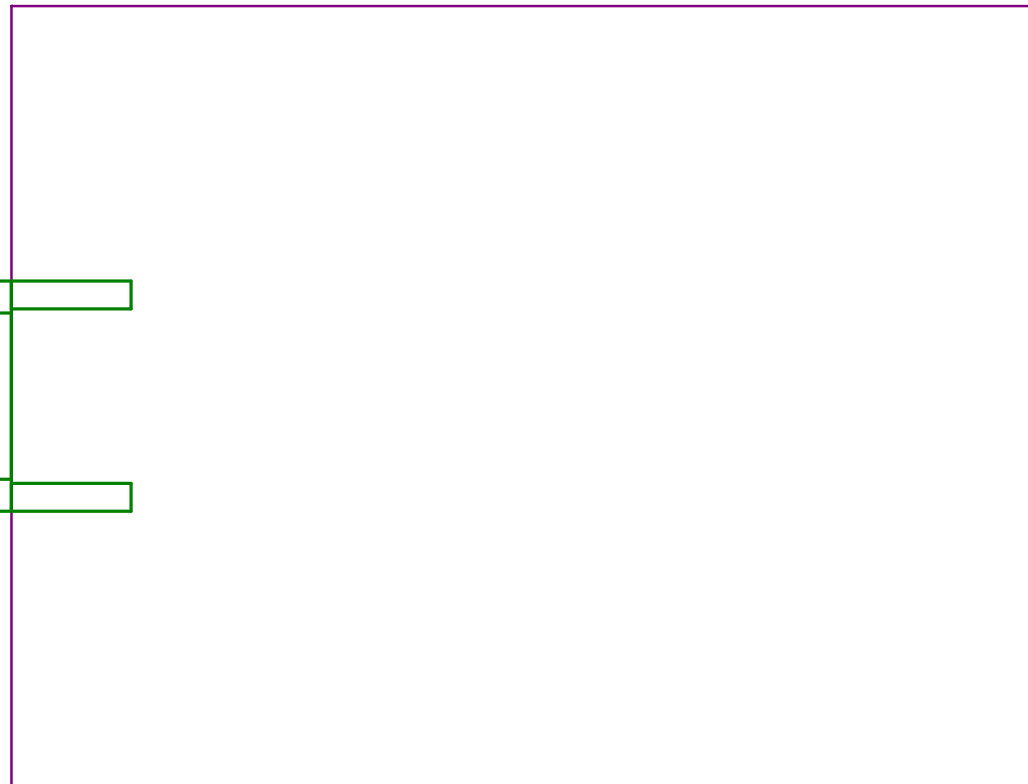
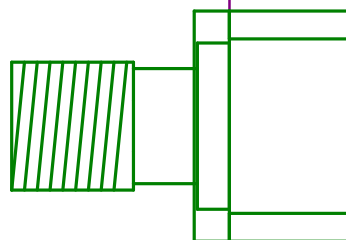






Project: STM32WB09_QFN32_2L_IPD		
Layer: Mechanical 14	Gerber: .GM14	
Variant: Variant A	Ref: MB2157	
Date: 07 July 2024	Rev: A	





Project: STM32WB09_QFN32_2L_IPD	
Layer: Mechanical 15	Gerber: .GM15
Variant: Variant A	Ref: MB2157
Date: 07 July 2024	Rev: A



